

TITLE OF THE INVENTION: SEMICONDUCTOR DEVICE AND METHOD FOR FORMING THE SAME

Abstract

A semiconductor device and a method for forming the same are provided. The semiconductor device may include: a first redistribution layer (RDL) having a first side and a second side opposite to the first side; at least one electronic component attached on the first side of the first RDL; a photonic component attached on the second side of the first RDL; a first plurality of conductive bumps formed on the second side of the first RDL and electrically coupled with the first RDL; a second RDL having a first side and a second side opposite to the first side, wherein the first side of the second RDL is electrically coupled with the first plurality of conductive bumps; a second plurality of conductive bumps formed on the second side of the second RDL and electrically coupled with the second RDL.

[FIG. 1]